

Title (en)  
METHOD OF ACTIVATING SURFACES FOR ELECTROLESS PLATING

Publication  
**EP 0043485 B1 19850515 (DE)**

Application  
**EP 81104782 A 19810622**

Priority  
DE 3025307 A 19800704

Abstract (en)  
[origin: EP0043485A1] 1. Process for activating metallic and non-metallic surfaces for the purpose of currentless metal deposition, characterized in that a) the surface to be metallized is wetted with an organometallic compound from the series comprising butadiene palladium dichloride, diacetonitrile palladium dichloride, diacetonitrile platinum dichloride and dibenzonitrile palladium dichloride, which compound is stable towards air and moisture and is dispersed in an organic solvent, b) the organic solvent is removed and c) the organometallic compound adhering to the surface to be metallized is reduced.

IPC 1-7  
**C23C 18/18**; **C23C 18/28**

IPC 8 full level  
**C23C 18/18** (2006.01); **C23C 18/28** (2006.01); **C23C 18/30** (2006.01)

CPC (source: EP)  
**C23C 18/30** (2013.01)

Citation (examination)

- The Organic Chemistry of Palladium (1971), Vol. I, Seite 137
- Chemistry of Coordination Compounds (1956), J.C. Bailar, Abschnitt 15, Seiten 487-508
- Comprehensive Inorganic Chemistry (1975), Band 3, Seite 1323

Cited by  
US5183611A; US4657786A; US4575467A; EP0163805A1; US4659592A; EP0214097A1; US4668533A; DE3938710A1; EP0082438B1

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**EP 81104782 A 19810622**; AT 81104782 T 19810622; CA 380974 A 19810702; DE 3025307 A 19800704; DE 3170482 T 19810622; ES 503645 A 19810703; JP 10347481 A 19810703